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TITLE: Employing on die temperature sensors and fan-heatsink
failure signals to control power dissipation
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REF-CITED:

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ART-UNIT: 251
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ABSTRACT:

A circuit and method for reducing an internal clocking frequency of the semiconductor device upon receiving a first signal indicating that a fan element disposed on the semiconductor device is operating at an unacceptable performance level and/or a second signal indicating that the semiconductor device is operating at a temperature greater than a prescribed boundary temperature.

22 Claims, 12 Drawing Figures